

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6690929

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUN-TING TSAI	12/02/2020
SREEVATSAN MADHAVAN	05/04/2021
SHANG-CHIH CHUANG	11/30/2020
KUANG-JUI HSU	03/12/2020
VENKATA RAVI KIRAN DAYANA	12/30/2020
XIAOYUN JIANG	12/02/2020
RECEIVING PARTY DATA	
Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17063541
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	LAHO@POL SINELLI.COM
Correspondent Name:	POL SINELLI
Address Line 1:	THREE EMBARCADERO CENTER
Address Line 2:	SUITE 2400
Address Line 4:	SAN FRANCISCO, CALIFORNIA 94111
ATTORNEY DOCKET NUMBER:	203595 (659056)
NAME OF SUBMITTER:	LINDSAY AHO
SIGNATURE:	/LINDSAY AHO/
DATE SIGNED:	05/04/2021
Total Attachments: 8	

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ASSIGNMENT

WHEREAS, WE,

1. Chung-Chi TSAI, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121,
2. Sreevatsan MADHAVAN, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121,
3. Shang-Chih CHUANG, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121,
4. Kuang-Jui HSU, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121,
5. Venkata Ravi Kiran DAYANA, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121,
6. Xiaoyun JIANG, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to SEGMENTATION FOR IMAGE EFFECTS (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I do hereby acknowledge that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS under the Patent Cooperation Treaty (PCT), and/or in the United States, including but not limited to International Patent Application and all provisional applications relating thereto, together with Non-U.S. Provisional Application No(s). 17/063,541, filed October 5, 2020, Qualcomm Reference No. 203595, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all nonprovisional applications, national phase applications, divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design

applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND I further do acknowledge and agree that I have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND I DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND I DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which I may be entitled, or that I may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND I HEREBY covenant and agree that I will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to me respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

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AND I HEREBY covenant that I will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, on 12/02/2000
City, State Date

Chung-Chi TSAI
Chung-Chi TSAI

Done at _____, on _____
City, State Date

Sreevatsan MADHAVAN

Done at _____, on _____
City, State Date

Shang-Chih CHUANG

Done at _____, on _____
City, State Date

Kuang-Jui HSU

Done at _____, on _____
City, State Date

Venkata Ravi Kiran DAYANA

Done at _____, on _____
City, State Date

Xiaoyun JIANG

AND I HEREBY covenant that I will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
City, State Date

Chung-Chi TSAI

Done at CHENNAI, TN, INDIA, on 05/04/2021
City, State Date

Sreevatsan
Sreevatsan MADHAVAN

Done at _____, on _____
City, State Date

Shang-Chih CHUANG

Done at _____, on _____
City, State Date

Kuang-Jui HSU

Done at _____, on _____
City, State Date

Venkata Ravi Kiran DAYANA

Done at _____, on _____
City, State Date

Xiaoyun JIANG

AND I HEREBY covenant that I will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
City, State Date Chung-Chi TSAI

Done at _____, on _____
City, State Date Sreevatsan MADHAVAN

Done at San Diego, CA, on 11/30/2020
City, State Date Shang-Chih Chuang
Shang-Chih CHUANG

Done at _____, on _____
City, State Date Kuang-Jui HSU

Done at _____, on _____
City, State Date Venkata Ravi Kiran DAYANA

Done at _____, on _____
City, State Date Xiaoyun JIANG

PATENT

Qualcomm Reference Number: **203595**

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AND I HEREBY covenant that I will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
City, State Date

Chung-Chi TSAI

Done at _____, on _____
City, State Date

Sreevatsan MADHAVAN

Done at _____, on _____
City, State Date

Shang-Chih CHUANG

Done at Hsinchu, Taiwan, on 03/12/2020
City, State Date

Kuang-Jui HSU
Kuang-Jui HSU

Done at _____, on _____
City, State Date

Venkata Ravi Kiran DAYANA

Done at _____, on _____
City, State Date

Xiaoyun JIANG

PATENT

REEL: 056128 FRAME: 0751

AND I HEREBY covenant that I will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
City, State Date Chung-Chi TSAI

Done at _____, on _____
City, State Date Sreevatsan MADHAVAN

Done at _____, on _____
City, State Date Shang-Chih CHUANG

Done at _____, on _____
City, State Date Kuang-Jui HSU

Done at San Diego, CA, on 12/30/2020
City, State Date D.V.R.V.
Venkata Ravi Kiran DAYANA

Done at _____, on _____
City, State Date Xiaoyun JIANG

AND I HEREBY covenant that I will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____ City, State Date	_____
	Chung-Chi TSAI
Done at _____, on _____ City, State Date	_____
	Sreevatsan MADHAVAN
Done at _____, on _____ City, State Date	_____
	Shang-Chih CHUANG
Done at _____, on _____ City, State Date	_____
	Kuang-Jui HSU
Done at _____, on _____ City, State Date	_____
	Venkata Ravi Kiran DAYANA
Done at <u>San Diego, CA</u> , on <u>Dec. 2nd, 2020</u> City, State Date	<u>Xiaoyun JIANG</u> Xiaoyun JIANG